



## **Product Summary**

| VBR (Min) | IPP (Max) | Сио (Тур) |
|-----------|-----------|-----------|
| 5V        | 5A        | 0.55pF    |

#### Description

The DT1240E-04LP is a high-performance device suitable for protecting four high-speed I/Os. These devices are assembled in U-DFN2510-10 package and have high ESD surge capability and low capacitance.

# Applications

Typically used at high-speed ports such as USB2.0, USB3.0, USB3.1, IEEE1394 (Firewire<sup>®</sup>, iLink), Serial ATA, DVI<sup>™</sup>, HDMI1.4<sup>™</sup>, HDMI2.0<sup>™</sup> and PCI<sup>™</sup>.

## Features

- Clamping Voltage: 7.5V at 10A 100ns, TLP 8.2V at 5A (8µs/20µs)
- IEC 61000-4-2 (ESD): Air ±14kV, Contact ±12kV
- IEC 61000-4-5 (Lighting): 5A (8µs/20µs)
- 4 Channels of ESD Protection
- Low Channel Input Capacitance of 0.55pF Typical
- TLP Dynamic Resistance: 0.2Ω
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.

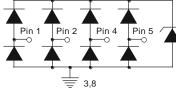
https://www.diodes.com/quality/product-definitions/

# **Mechanical Data**

- Case: U-DFN2510-10
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- **Terminal Connections: See Schematic**
- Terminals: Finish NiPdAu, Solderable per MIL-STD-202, Method 208 @4)
- Weight: 0.038 grams (Approximate)

| r | Description  | ] [ | 10   | 9        | 8   | 7        | 6        | -   |          | -        |   |
|---|--------------|-----|------|----------|-----|----------|----------|-----|----------|----------|---|
|   | I/O          |     |      |          | ,   |          |          |     | Pin 1    | Pin 2    |   |
| N | o Connection |     | 1771 | $(\Box)$ | f h | $(\Box)$ | $(\Box)$ | -   | <b>T</b> | <b>↓</b> | ł |
| V | SS           |     | 1    | 2        | 3   | 4        | 5        | · · |          |          | + |

Pin Description (Top View)



**Device Schematic** 

# Ordering Information (Note 4)

| Part Number    | Compliance | Marking | Reel Size (inches) | Tape Width (mm) | Quantity per Reel |
|----------------|------------|---------|--------------------|-----------------|-------------------|
| DT1240E-04LP-7 | Standard   | MW5     | 7                  | 8               | 3,000/Tape & Reel |

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

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# **Marking Information**

| MW5 | YM |
|-----|----|
|-----|----|

 $\begin{array}{l} MW5 = Product Type Marking Code \\ YM = Date Code Marking \\ Y = Year (ex: I = 2021) \\ M = Month (ex: 9 = September) \end{array}$ 

Date Code Key

| Year  | 2017 |     | 2021 | 2022 | 2023 | 2024 | 2025 | 2026 | 2027 | 2028 | 2029 | 2030 |
|-------|------|-----|------|------|------|------|------|------|------|------|------|------|
| Code  | E    |     |      | J    | K    | L    | М    | Ν    | 0    | Р    | R    | S    |
|       |      |     |      |      |      |      |      |      |      |      |      |      |
| Month | Jan  | Feb | Mar  | Apr  | Мау  | Jun  | Jul  | Aug  | Sep  | Oct  | Nov  | Dec  |

## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic  | Symbol          | Value       | Unit | Conditions                      |
|---|-----------------|-------------|------|---------------------------------|
| Peak Pulse Current, per IEC 61000-4-5                 | IPP             | 5           | A    | I/O to Vss, 8/20µs              |
| Peak Pulse Power, per IEC 61000-4-5                   | P <sub>PP</sub> | 47          | W    | I/O to V <sub>SS</sub> , 8/20µs |
| ESD Protection – Contact Discharge, per IEC 61000-4-2 | Vesd_contact    | ±12         | kV   | I/O to Vss                      |
| ESD Protection – Air Discharge, per IEC 61000-4-2     | Vesd_air        | ±14         | kV   | I/O to Vss                      |
| Operating Temperature                                 | T <sub>OP</sub> | -55 to +85  | °C   | —                               |
| Storage Temperature                                   | Tstg            | -55 to +150 | °C   | —                               |

# **Thermal Characteristics**

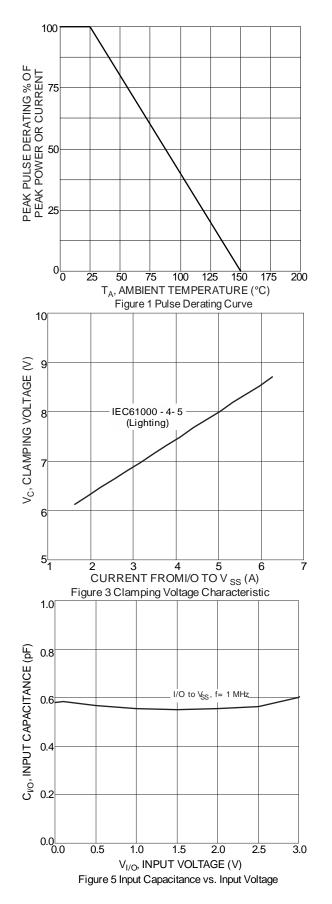
| Characteristic   | Symbol | Value | Unit |
|--|--------|-------|------|
| Power Dissipation Typical (Note 5)                       | PD     | 350   | mW   |
| Thermal Resistance, Junction to Ambient Typical (Note 5) | Reja   | 360   | °C/W |

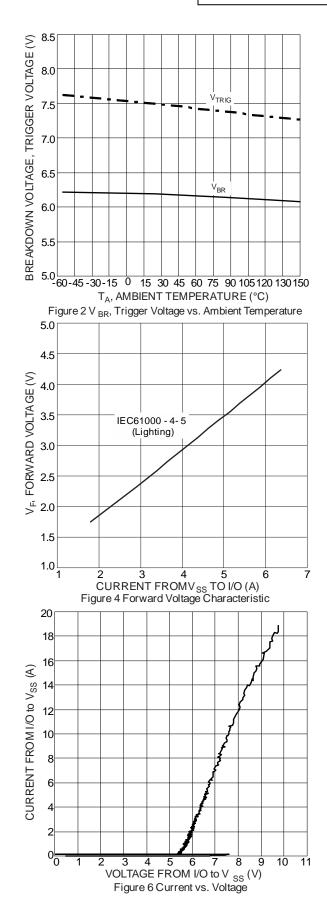
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic                    | Symbol             | Min  | Тур   | Max  | Unit | Test Conditions  |
|-----------------------------------|--------------------|------|-------|------|------|--|
| Reverse Working Voltage           | VRWM               | _    | _     | 3.3  | V    | —  |
| Reverse Current                   | IR                 | _    | _     | 1.0  | μA   | $V_R = 3.3V$ , I/O to Vss                                |
| Reverse Breakdown Voltage         | VBR                | 5    | _     | _    | V    | I <sub>R</sub> = 1mA, I/O to Vss                         |
| Forward Clamping Voltage          | VF                 | -1.0 | -0.85 | _    | V    | $I_F = -15 \text{mA}$ , I/O to $V_{SS}$                  |
| Reverse Clamping Voltage (Note 6) | Vc                 | _    | 8.2   | 9.5  | V    | IPP = 5A, I/O to Vss, 8/20µs                             |
| ESD Clamping Voltage              | Vesd               | _    | 7.5   | _    | V    | TLP, 10A, t <sub>P</sub> = 100ns, I/O to Vss             |
| Dynamic Reverse Resistance        | R <sub>DIF-R</sub> | _    | 0.2   | _    | Ω    | TLP, 10A, $t_P$ = 100ns, I/O to V <sub>SS</sub>          |
| Dynamic Forward Resistance        | Rdif-f             | _    | 0.2   | _    | Ω    | TLP, 10A, t <sub>P</sub> = 100ns, V <sub>SS</sub> to I/O |
| Channel Input Capacitance         | CI/O               | _    | 0.55  | 0.65 | pF   | V <sub>I/O</sub> = 2.5V, V <sub>SS</sub> = 0V, f = 1MHz  |
| Delta CI/O                        | CI/OMAX-CI/OMIN    | _    | 0.04  |      | pF   | CI/OMAX-CI/OMIN  |

Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes Incorporated's website at http://www.diodes.com/package-outlines.html. 6. Clamping voltage value is based on an 8x20µs peak pulse current (I<sub>PP</sub>) waveform.



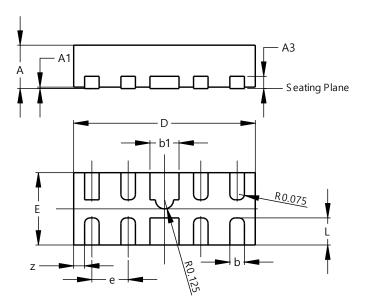






# **Package Outline Dimensions**

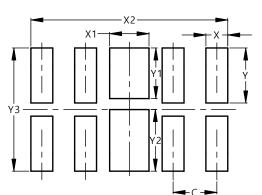
Please see http://www.diodes.com/package-outlines.html for the latest version.



|     | U-DFN    | 2510-10  |       |
|-----|----------|----------|-------|
| Dim | Min      | Max      | Тур   |
| Α   | 0.545    | 0.605    | 0.575 |
| A1  | 0.00     | 0.05     | 0.03  |
| A3  | -        | -        | 0.13  |
| b   | 0.15     | 0.25     | 0.20  |
| b1  | 0.35     | 0.45     | 0.40  |
| D   | 2.450    | 2.575    | 2.500 |
| е   | -        | -        | 0.50  |
| Е   | 0.950    | 1.075    | 1.000 |
| L   | 0.325    | 0.425    | 0.375 |
| z   | -        | -        | 0.150 |
| AI  | l Dimens | sions in | mm    |

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



U-DFN2510-10

U-DFN2510-10

| Dimensions | Value<br>(in mm) |  |  |  |
|------------|------------------|--|--|--|
| С          | 0.500            |  |  |  |
| Х          | 0.250            |  |  |  |
| X1         | 0.450            |  |  |  |
| X2         | 2.250            |  |  |  |
| Y          | 0.625            |  |  |  |
| Y1         | 0.575            |  |  |  |
| Y2         | 0.700            |  |  |  |
| Y3         | 1.400            |  |  |  |

DT1240E-04LP

Document number: DS39294 Rev. 2 - 2



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